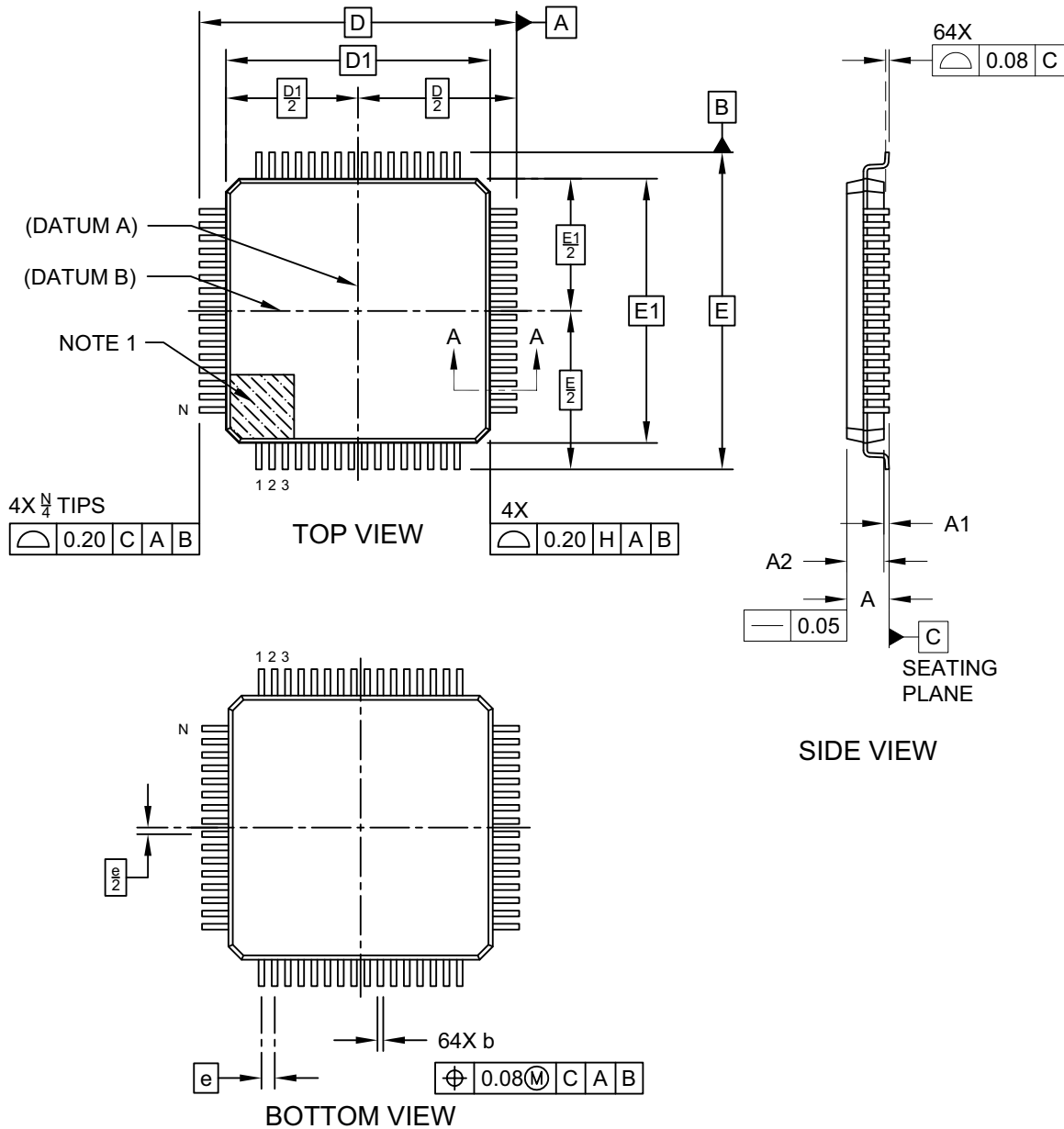


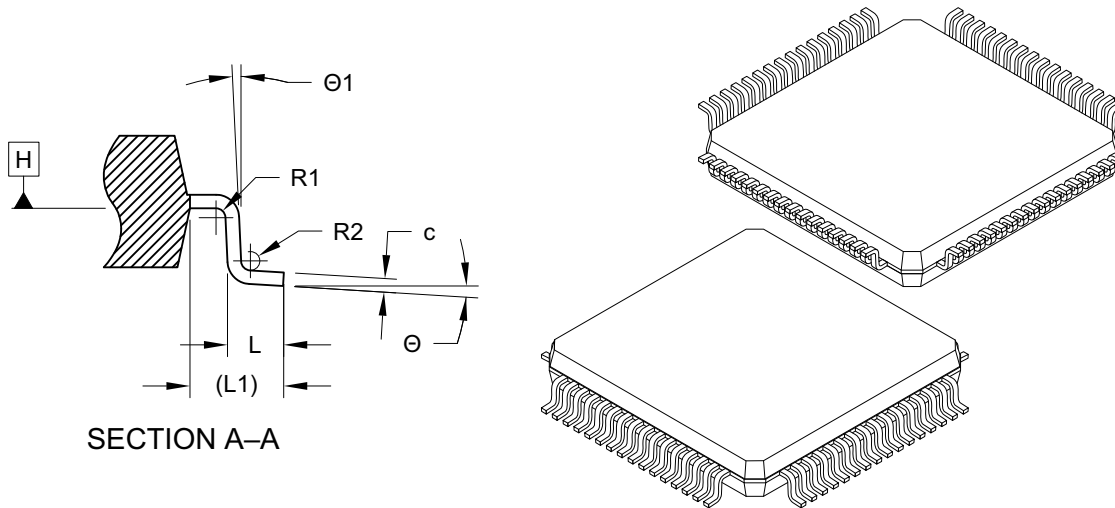
64-Lead Low Profile Plastic Quad Flatpack (PL) - 10x10 mm Body [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N	64			
Pitch	e	0.50 BSC			
Overall Height	A	-	-	1.60	
Standoff	A1	0.05	-	0.15	
Molded Package Thickness	A2	1.35	1.40	1.45	
Overall Length	D	12.00 BSC			
Molded Package Length	D1	10.00 BSC			
Overall Width	E	12.00 BSC			
Molded Package Width	E1	10.00 BSC			
Terminal Width	b	0.17	0.22	0.27	
Terminal Thickness	c	0.09	-	0.20	
Terminal Length	L	0.45	0.60	0.75	
Footprint	L1	1.00 REF			
Bend Radius	R1	0.08	-	-	
Bend Radius	R2	0.08	-	-	
Lead Angle	Θ1	0°	-	-	
Foot Angle	Θ	0°	3.5°	7°	

Notes:

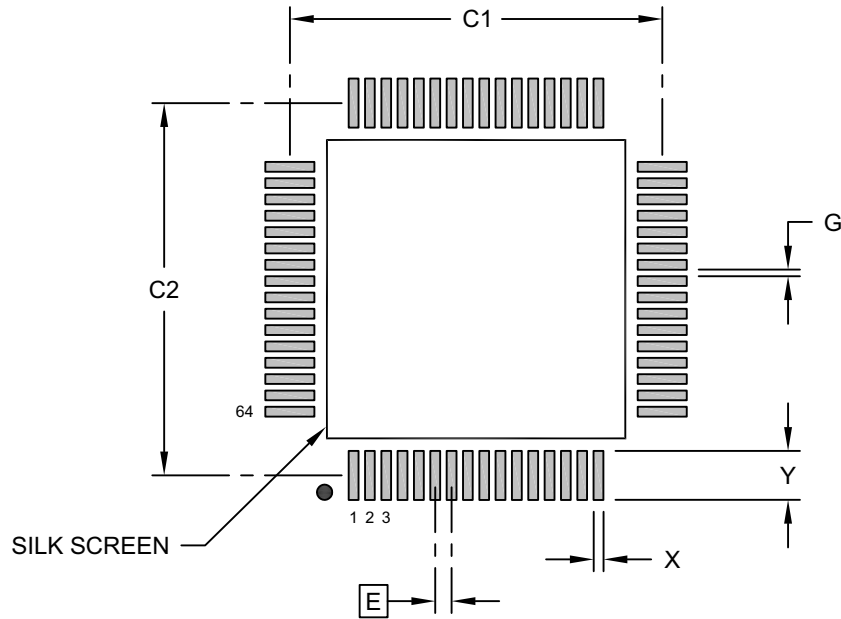
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

64-Lead Low Profile Plastic Quad Flatpack (PL) - 10x10 mm Body [LQFP]

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RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X			0.30
Contact Pad Length (X64)	Y			1.50
Contact Pad to Contact Pad (X60)	G	0.20		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2053A